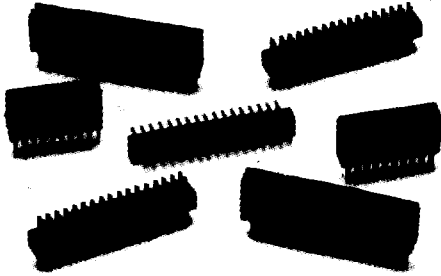


High Density Connector System



Features:

- .050" (1.27mm) pitch.
- Mates with .018" (.46 mm) square terminals.
- BeCu contacts.
- Selective gold plating.
- Low insertion force.
- Vapor phase and infrared compatible.
- Standoff devices.
- Closed entry.
- Mates with .050" (1.27 mm) square headers (see next page).
- Consult factory for specifications.

Plating:

G - 10µ" Gold minimum over 50µ" Nickel minimum

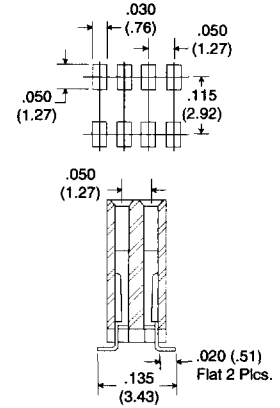
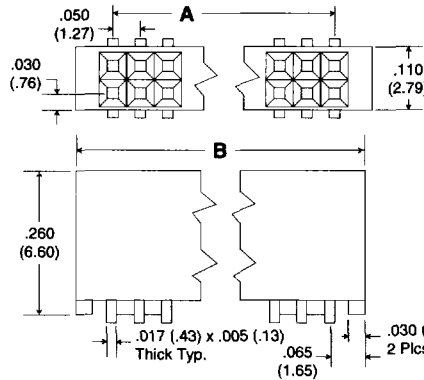
TG - 30µ" Gold minimum over 50µ" Nickel minimum on contact area only, 100µ" Tin-Lead tail

Body Material:

GF PPS, U.L. Rated 94V-O

Surface Mount .050" (1.27mm) Pitch Receptacle

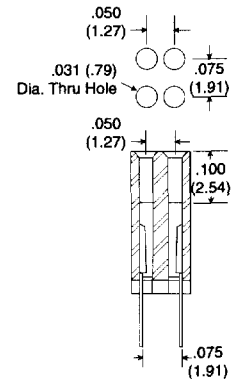
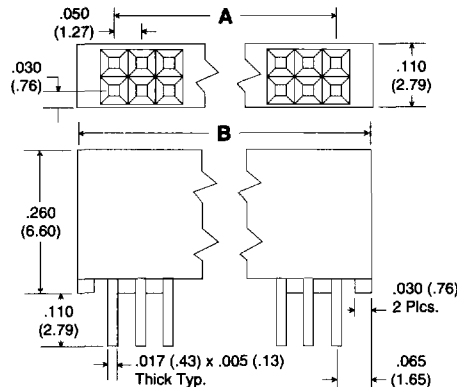
BD XXX - 212 XX



A = Number of Positions Per Row x .050" (1.27mm) + .050" (1.27mm)
B = Number of Positions Per Row Minus 1 x .050" (1.27mm)

Thru Hole .050" (1.27mm) Pitch Receptacle

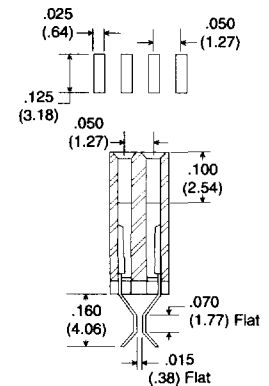
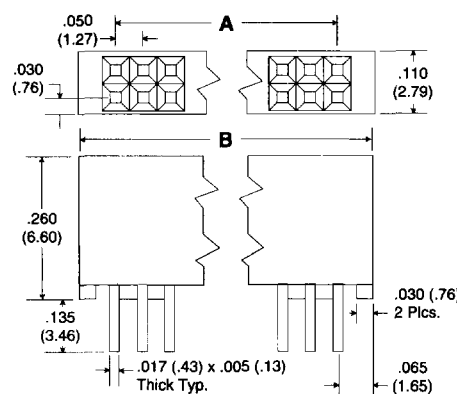
BD XXX - 211 XX



A = Number of Positions Per Row x .050" (1.27mm) + .050" (1.27mm)
B = Number of Positions Per Row Minus 1 x .050" (1.27 mm)

Edge Mount .050" (1.27mm) Pitch Receptacle

BD XXX - 469 XX



A = Number of Positions Per Row x .050" (1.27mm) + .050" (1.27mm)
B = Number of Positions Per Row Minus 1 x .050" (1.27mm)

